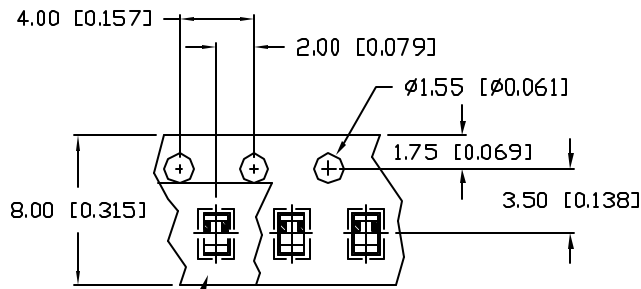
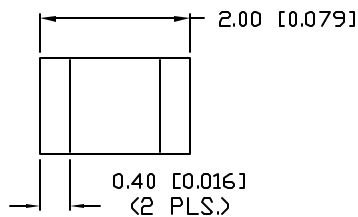
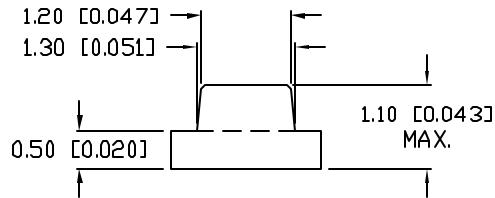
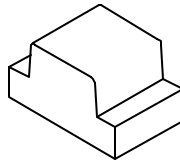
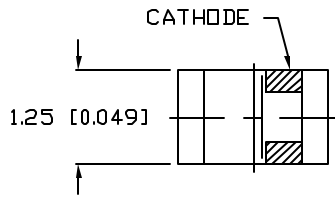


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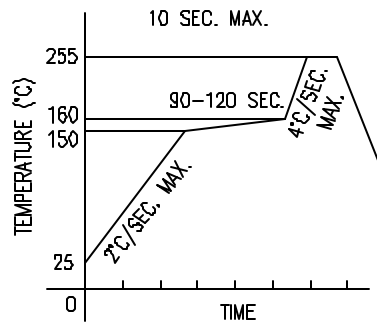
PART NUMBER		REV.
SML-LXF0805GC-TR		B

REV.	E.C.N. NUMBER AND REVISION COMMENTS	DATE
A	E.C.N. #10967.	3.14.03
B	E.C.N. #11148.	2.14.05



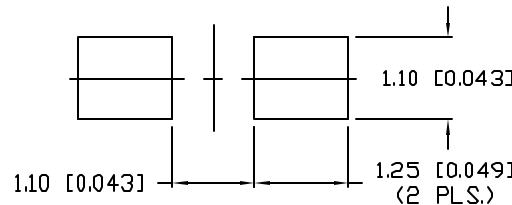
TOP TAPE
TAPE FEED DIRECTION →

LEAD FREE REFLOW PROFILE



TOTAL TIME ABOVE 220°C IS 60 SECONDS MAX.

RECOMMENDED SOLDER PAD LAYOUT



ELECTRO-OPTICAL CHARACTERISTICS $T_A=25^\circ\text{C}$ $I_f=20\text{mA}$

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		565		nm	
FORWARD VOLTAGE		2.2	2.6	V_f	
REVERSE VOLTAGE	5.0			V_r	$I_f=100\mu\text{A}$
AXIAL INTENSITY		12		mod	$I_f=20\text{mA}$
VIEWING ANGLE		120		2x theta	
EMITTED COLOR:	GREEN				
EPOXY LENS FINISH:	WATER CLEAR				

LIMITS OF SAFE OPERATION AT 25°C

PARAMETER	MAX	UNITS
PEAK FORWARD CURRENT*	150	mA
STEADY CURRENT	25	mA
POWER DISSIPATION	100	mW
DERATE FROM 25°C	-1.2	mW/°C
OPERATING TEMP.	-30 TO +85	°C
STORAGE TEMP.	-40 TO +85	°C

* $t < 10\mu\text{s}$

NOTES:

- THE POLARITY MARK IS ORIENTED TOWARDS THE TAPE SPROCKET HOLE.

CAUTION: MOISTURE SENSITIVE DEVICE
PER JEDEC LEVEL 4 STANDARDS



*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), X.X=±0.5 (±0.020), X.XX=±0.25 (±0.010), X.XXX=±0.127 (±0.005). LEAD SIZE=±0.05 (0.002), LEAD LENGTH=±0.75 (±0.030). MIN. +0.00 -0.00 MAX. +0.00 -0.00

UNCONTROLLED DOCUMENT

REV.	PART NUMBER
B	SML-LXF0805GC-TR

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2.0mm x 1.25mm SURFACE MOUNT LED,
565nm GREEN LED,
WATER CLEAR LENS, TAPE AND REEL

RELIABILITY NOTE
OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN BY:	CHECKED BY:	APPROVED BY:	DATE: 3.26.02
BC			PAGE: 1 OF 1
			SCALE: N/A